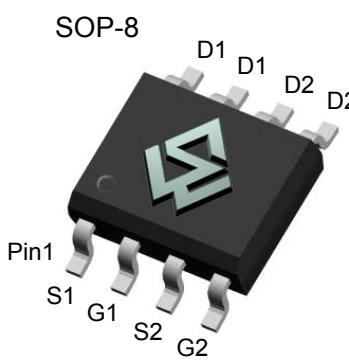
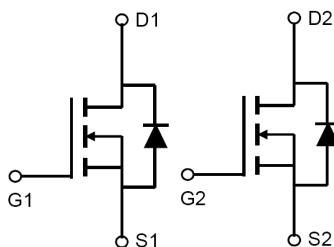


30V Dual N-Channel Enhancement-Mode MOSFET

General Description	Product Summary	
<ul style="list-style-type: none"> • Low gate charge. • Use as a load switch. • Use in PWM applications 	<ul style="list-style-type: none"> • BV_{DSS} 30V • $R_{DS(on)}$ @$VGS = 10V$ < 28mΩ • $R_{DS(on)}$ @$VGS = 4.5V$ < 35mΩ 	
		

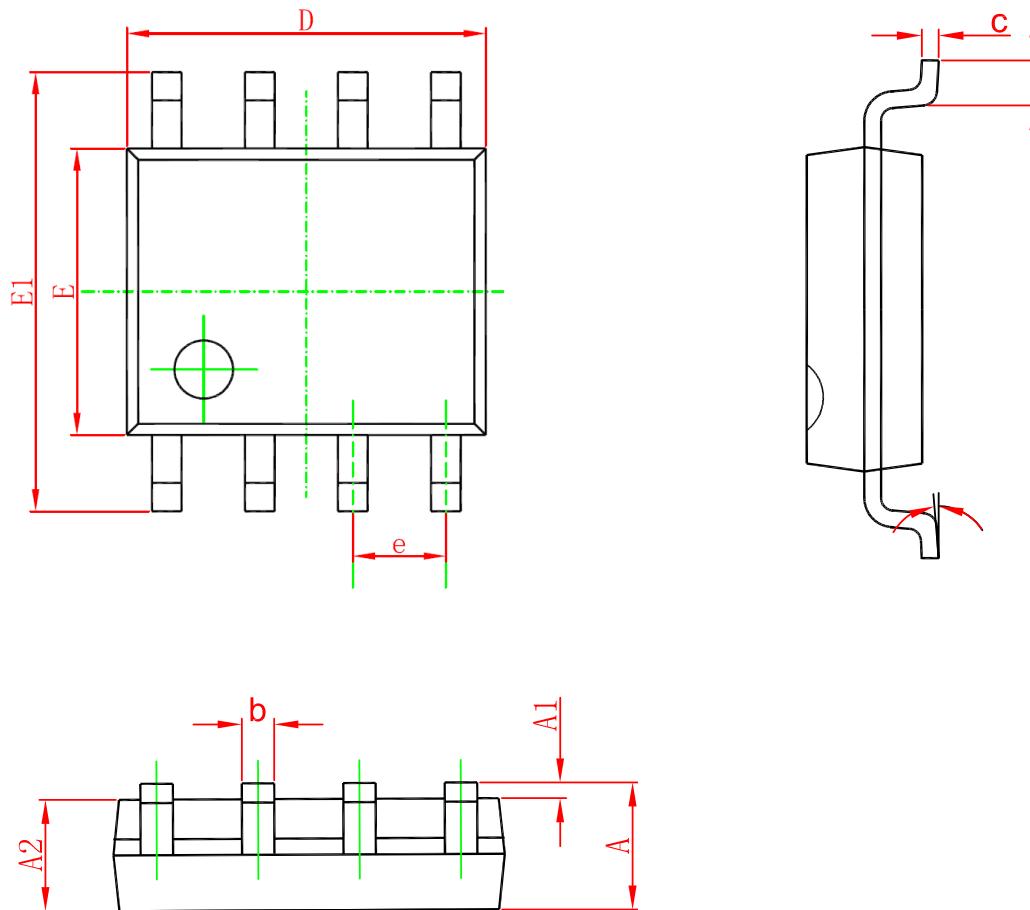
Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)				
Parameter	Symbol	Maximum	Units	
Drain-Source Voltage	V_{DS}	30	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current ($T_A=25^\circ C$)	I_D	6.0	A	
Drain Current ($T_A=75^\circ C$)		4.8	A	
Pulsed Drain Current ^a	I_{DM}	30	A	
Power Dissipation ^b ($T_A=25^\circ C$)	P_D	2.0	W	
Power Dissipation ^b ($T_A=75^\circ C$)		1.4	W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150	°C	

Thermal Characteristics				
Parameter	Symbol	Maximum	Units	
Junction-to-Ambient ^a ($t \leq 10s$)	$R_{\theta JA}$	50	°C/W	
Junction-to-Ambient ^{a,d} (Steady-State)		90	°C/W	
Junction-to-Lead (Steady-State)	$R_{\theta JL}$	25	°C/W	

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 30\text{V}$, $V_{\text{GS}} = 0\text{V}$			1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 20\text{V}$, $V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$	1		2.5	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance	$V_{\text{GS}} = 10\text{V}$, $I_D = 6.0\text{A}$		18	28	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}$, $I_D = 5.0\text{A}$		22	35	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{\text{DS}} = 5.0\text{V}$, $I_D = 6.0\text{A}$		20		S
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{\text{GS}} = 0\text{V}$, $I_S = 1.0\text{A}$			1.1	V
I_S	Maximum Body-Diode Continuous Current				2.5	A
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}} = 15\text{V}$, $V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		802		pF
C_{oss}	Output Capacitance			105		pF
C_{rss}	Reverse Transfer Capacitance			85		pF
Switching Characteristics						
Q_g	Total Gate Charge	$V_{\text{DS}} = 15\text{V}$, $I_D = 6.0\text{A}$ $V_{\text{GS}} = 10\text{V}$		12.8		nC
Q_{gs}	Gate-Source Charge			4.5		nC
Q_{gd}	Gate-Drain Charge			3.8		nC
$t_{\text{D(ON)}}$	Turn-On Delay Time	$V_{\text{DD}} = 15\text{V}$, $I_D = 1\text{A}$ $V_{\text{GS}} = 10\text{V}$ $R_{\text{GEN}} = 3\text{ohm}$		6.2		ns
t_r	Turn-On Rise Time			4.8		ns
$t_{\text{D(OFF)}}$	Turn-Off Delay Time			14.5		ns
t_f	Turn-Off Fall Time			3.5		ns

- a. Repetitive rating, Pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$
- b. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-ambient thermal resistance.
- c. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- d. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

SOP-8 Package Outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

单击下面可查看定价，库存，交付和生命周期等信息

>>[SiliconWisdom\(矽睿半导体\)](#)